



256Kx16 PLASTIC MONOLITHIC SRAM

FEATURES

- 256Kx16 bit CMOS Static
- Random Access Memory
 - Access Times of 15, 17, 20, 25ns
 - Data Retention Function (LPA version)
 - TTL Compatible Inputs and Outputs
 - Fully Static, No Clocks
- Center Power/Ground Pins (Revolutionary)
- 44 lead JEDEC Approved Revolutionary Pinout
 - Plastic SOJ Package
- Single +5V ($\pm 10\%$) Supply Operation

The EDI816256CA is a ruggedized plastic 256Kx16 SRAM that allows the user to capitalize on the cost advantage of using a plastic component while not sacrificing all of the reliability available in a full military device.

The EDI816256CA uses 16 common input and output lines and has an output enable pin which operates faster than address access time at read cycle. The device allows upper and lower byte access by use of the data byte control pins ($\overline{LB}$, $\overline{UB}$).

Extended temperature testing is performed with the test patterns developed for use on WEDC's fully compliant 256Kx16 SRAMs. WEDC fully characterizes devices to determine the proper test patterns for testing at temperature extremes. This is critical because the operating characteristics of device change when it is operated beyond the commercial guarantee a device that operates reliably in the field at temperature extremes. Users of WEDC's ruggedized plastic benefit from WEDC's extensive experience in characterizing SRAMs for use in military systems.

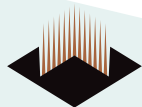
WEDC ensures Low Power devices will retain data in Data Retention mode by characterizing the devices to determine the appropriate test conditions. This is crucial for systems operating at -40°C or below and using dense memories such as 256Kx16s. WEDC's ruggedized plastic SOJ is footprint compatible with WEDC's full military ceramic 44 pin SOJ.

PIN CONFIGURATION TOP VIEW

A0	1	44	A17
A1	2	43	A16
A2	3	42	A15
A3	4	41	$\overline{OE}$
A4	5	40	$\overline{UB}$
$\overline{CS}$	6	39	$\overline{LB}$
I/O1	7	38	I/O16
I/O2	8	37	I/O15
I/O3	9	36	I/O14
I/O4	10	35	I/O13
V _{cc}	11	34	V _{ss}
V _{ss}	12	33	V _{cc}
I/O5	13	32	I/O12
I/O6	14	31	I/O11
I/O7	15	30	I/O10
I/O8	16	29	I/O9
$\overline{WE}$	17	28	NC
A5	18	27	A14
A6	19	26	A13
A7	20	25	A12
A8	21	24	A11
A9	22	23	A10

PIN DESCRIPTION

A0-17	Address Inputs
$\overline{LB}$	Lower-Byte Control (I/O1-8)
$\overline{UB}$	Upper-Byte Control (I/O9-16)
I/O1-16	Data Input/Output
$\overline{CS}$	Chip Select
$\overline{OE}$	Output Enable
$\overline{WE}$	Write Enable
V _{cc}	+5.0V Power
V _{ss}	Ground
NC	No Connection



TRUTH TABLE

$\overline{CS}$	$\overline{WE}$	$\overline{OE}$	$\overline{LB}$	$\overline{UB}$	Mode	Data I/O		Power
						I/O1-8	I/O9-16	
H	X	X	X	X	Not Select	High Z	High Z	Standby
L	H	H	X	X	Output Disable	High Z	High Z	Active
L	X	X	H	H				
L	H	L	L	H	Read	Data Out	High Z	Active
			H	L		High Z	Data Out	
			L	L		Data Out	Data Out	
L	L	X	L	H	Write	Data In	High Z	Active
			H	L		High Z	Data In	
			L	L		Data In	Data In	

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature (Mil.)	T_A	-55	+125	°C
Operating Temperature (Ind.)	T_A	-40	+85	°C
Storage Temperature	T_{STG}	-65	+150	°C
Signal Voltage Relative to V_{SS}	V_G	-0.5	$V_{CC} + 0.5$	V
Supply Voltage	V_{CC}	-0.5	7.0	V

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V_{CC}	4.5	5.5	V
Input High Voltage	V_{IH}	2.2	$V_{CC} + 0.5$	V
Input Low Voltage	V_{IL}	-0.3	+0.8	V
Operating Temperature (Mil.)	T_A	-55	+125	°C
Operating Temperature (Ind.)	T_A	-40	+85	°C

CAPACITANCE

($T_A = +25^\circ\text{C}$)

Parameter	Symbol	Condition	Max	Unit
Input capacitance	C_{IN}	$V_{IN} = 0V, f = 1.0\text{MHz}$	6	pF
Output capacitance	C_{OUT}	$V_{OUT} = 0V, f = 1.0\text{MHz}$	8	pF

This parameter is guaranteed by design but not tested.

DC CHARACTERISTICS

($V_{CC} = 5.0V, V_{SS} = 0V, T_A = -55^\circ\text{C}$ to $+125^\circ\text{C}$)

Parameter	Sym	Conditions	Min	Max	Units
Operating Power Supply Current	I_{CC1}	$\overline{WE}, \overline{CS} = V_{IL}, I_{I/O} = 0\text{mA}, \text{Min Cycle}$	—	300	mA
Standby (TTL) Power Supply Current	I_{CC2}	$\overline{CS} \geq V_{IH}, V_{IN} \leq V_{IL}, V_{IN} \geq V_{IH}$	—	60	mA
Full Standby Power Supply Current	I_{CC3}	$\overline{CS} \geq V_{CC} - 0.2V$	CA	25	mA
		$V_{IN} \geq V_{CC} - 0.2V$ or $V_{IN} \leq 0.2V$	LPA	15	mA
Input Leakage Current	I_{LI}	$V_{IN} = 0V$ to V_{CC}	-10	10	μA
Output Leakage Current	I_{LO}	$V_{I/O} = 0V$ to V_{CC}	-10	10	μA
Output High Voltage	V_{OH}	$I_{OH} = -4\text{mA}$	2.4	—	V
Output Low Voltage	V_{OL}	$I_{OL} = 8\text{mA}$	—	0.4	V



AC CHARACTERISTICS

(V_{CC} = 5.0V, V_{SS} = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	-15		-17		-20		-25		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Read Cycle										
Read Cycle Time	t _{RC}	15		17		20		25		ns
Address Access Time	t _{AA}		15		17		20		25	ns
Output Hold from Address Change	t _{OH}	0		0		0		0		ns
Chip Select Access Time	t _{ACS}		15		17		20		25	ns
Output Enable to Output Valid	t _{OE}		10		10		10		12	ns
Chip Select to Output in Low Z	t _{CLZ} ¹	5		5		5		5		ns
Output Enable to Output in Low Z	t _{OLZ} ¹	0		0		0		0		ns
Chip Disable to Output in High Z	t _{CHZ} ¹		7		7		7		8	ns
Output Disable to Output in High Z	t _{OHZ} ¹		7		7		7		8	ns
$\overline{\text{LB}}$, $\overline{\text{UB}}$ Access Time	t _{BA}		10		10		10		12	ns
$\overline{\text{LB}}$, $\overline{\text{UB}}$ Enable to Low Z Output	t _{BLZ} ¹	0		0		0		0		ns
$\overline{\text{LB}}$, $\overline{\text{UB}}$ Disable to High Z Output	t _{BHZ} ¹		7		7		7		8	ns

1. This parameter is guaranteed by design but not tested.

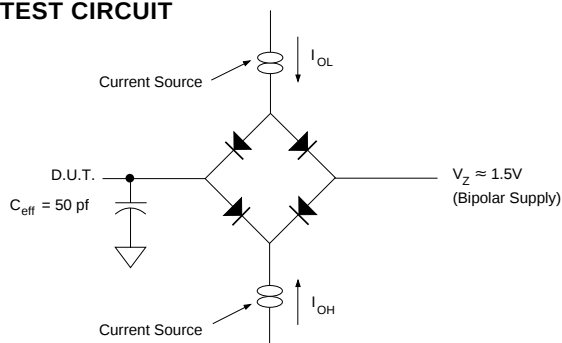
AC CHARACTERISTICS

(V_{CC} = 5.0V, V_{SS} = 0V, T_A = -55°C to +125°C)

Parameter	Symbol	-15		-17		-20		-25		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
Write Cycle										
Write Cycle Time	t _{WC}	15		17		20		25		ns
Chip Select to End of Write	t _{CW}	12		15		15		17		ns
Address Valid to End of Write	t _{AW}	12		15		15		17		ns
Data Valid to End of Write	t _{DW}	10		10		10		12		ns
Write Pulse Width	t _{WP}	12		15		15		17		ns
Address Setup Time	t _{AS}	0		0		0		0		ns
Address Hold Time	t _{AH}	0		0		0		0		ns
Output Active from End of Write	t _{OW} ¹	0		0		0		0		ns
Write Enable to Output in High Z	t _{WHZ} ¹		8		8		8		8	ns
Data Hold Time	t _{DH}	0		0		0		0		ns
$\overline{\text{LB}}$, $\overline{\text{UB}}$ Valid to End of Write	t _{BW}	12		15		16		18		ns

1. This parameter is guaranteed by design but not tested.

AC TEST CIRCUIT



AC TEST CONDITIONS

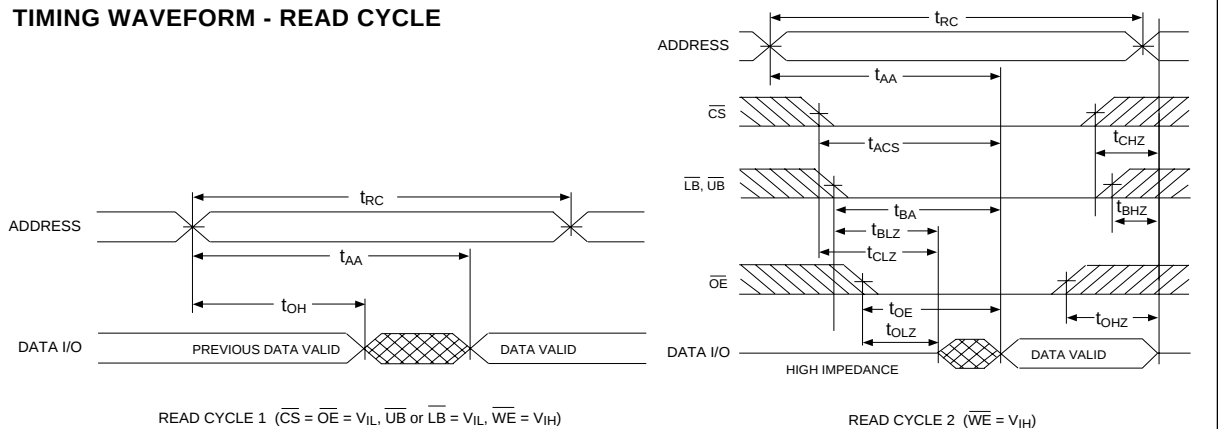
Parameter	Typ	Unit
Input Pulse Levels	V _{IL} = 0, V _{IH} = 3.0	V
Input Rise and Fall	5	ns
Input and Output Reference Level	1.5	V
Output Timing Reference Level	1.5	V

NOTES:

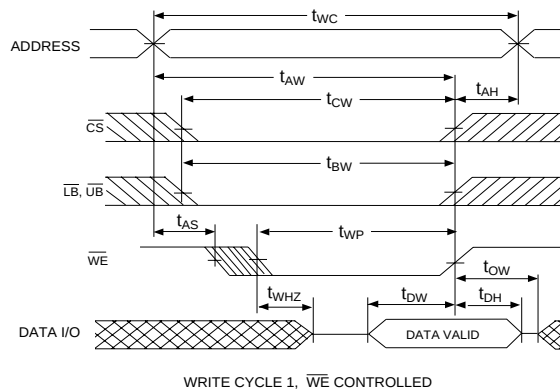
V₂ is programmable from -2V to +7V.
I_{OL} & I_{OH} programmable from 0 to 16mA.
Tester Impedance Z₀ = 75 Ω.
V₂ is typically the midpoint of V_{OH} and V_{OL}.
I_{OL} & I_{OH} are adjusted to simulate a typical resistive load circuit.
ATE tester includes jig capacitance.



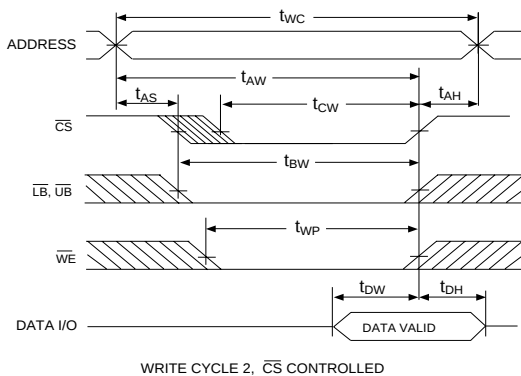
TIMING WAVEFORM - READ CYCLE



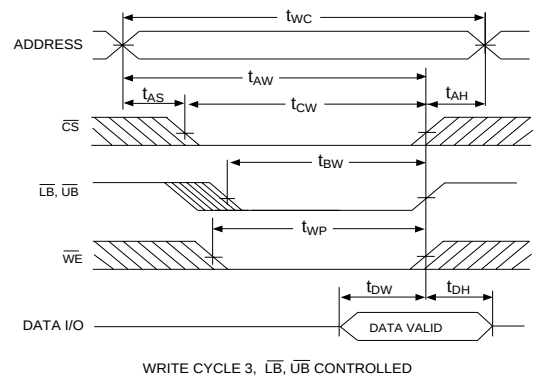
WRITE CYCLE - $\overline{WE}$ CONTROLLED



WRITE CYCLE - $\overline{CS}$ CONTROLLED

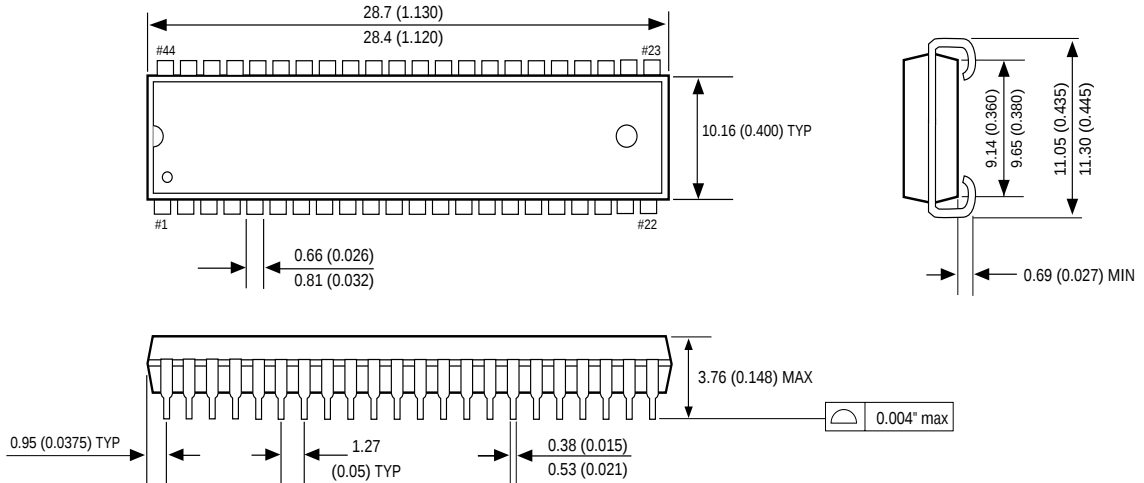


WRITE CYCLE - $\overline{LB}$, $\overline{UB}$ CONTROLLED





44 LEAD, PLASTIC SOJ (400 mil)



DIMENSIONS IN MILLIMETERS AND (INCHES)

ORDERING INFORMATION

EDI 8 16 256 CA X X X

WHITE ELECTRONIC DESIGNS _____

SRAM _____

ORGANIZATION, 256Kx16 _____

TECHNOLOGY: _____
CA = CMOS Standard Power
LPA = Low Power

ACCESS TIME (ns) _____

PACKAGE TYPE: _____
M44 = 44 lead Plastic SOJ

DEVICE GRADE: _____
B = MIL-STD-883 Compliant
M = Military Screened -55°C to +125°C
I = Industrial -40°C to +85°C
C = Commercial 0°C to +70°C